Device and method for bonding substrates

Abstract

The present invention relates to a method for bonding a first substrate (4o) with a second substrate (4u) at mutually facing contact faces (4k) of the substrates (4o, 4u) with the following steps, in particular the following sequence:

- holding of the first substrate (4o) to a first holding surface (1s, 1s', 1s", 1s''') of a first holding device (1, 1‘ 1", 1''', 1^{IV}, 1^{V}, 1^{VI}) and holding of the second substrate (4u) to a second holding surface (1s, 1s', 1s", 1s''') of a second holding device (1, 1‘ 1", 1''', 1^{IV}, 1^{V}, 1^{VI}),
- curvature of the contact faces (4k) before contacting of the contact faces (4k),

characterised in that
a change in curvature of the contact face (4k) of the first substrate (4o) and/or a change in curvature of the contact face (4k) of the second substrate (4u) are controlled during the bonding.

Furthermore, the present invention relates to a corresponding device.

Figure 4c in respect hereof.